

**DXTN07100BP5**

**100V NPN MEDIUM POWER LOW SATURATION TRANSISTOR**  
**PowerDI<sup>®</sup>5**

**Features**

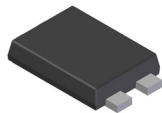
- $BV_{CEO} > 100V$
- $I_C = 2A$  High Continuous Collector Current
- $I_{CM} = 6A$  Peak Collector Current
- $P_D$  up to 3.2W
- 43% smaller than SOT223; 60% smaller than TO252
- Maximum height just 1.1mm
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

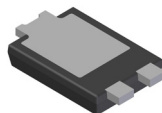
- Case: PowerDI5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ③
- Weight: 0.093 grams (approximate)

**Applications**

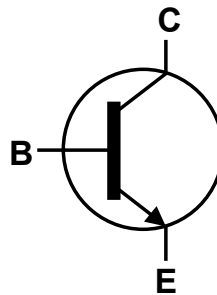
- Voltage Regulator using Emitter-Follower
- DC-DC Converter
- Telecoms
- Power Management



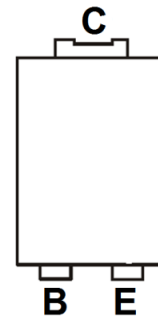
Top View



Bottom View



Device Schematic



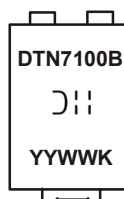
Top View  
Pin-Out


**Ordering Information** (Note 4)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DXTN07100BP5-13	AEC-Q101	DTN7100B	13	16	5,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>

**Marking Information**



- DTN7100B = Product Type Marking Code
-  = Manufacturers' Code Marking
- K = Factory Designator
- YYWW = Date Code Marking
- YY = Last Two Digits of Year (ex: 09 for 2009)
- WW = Week code (01 to 53)

**Absolute Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	120	V
Collector-Emitter Voltage	$V_{CEO}$	100	V
Emitter-Base Voltage	$V_{EBO}$	7	V
Continuous Collector Current	$I_C$	2	A
Peak Pulse Current	$I_{CM}$	6	A

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

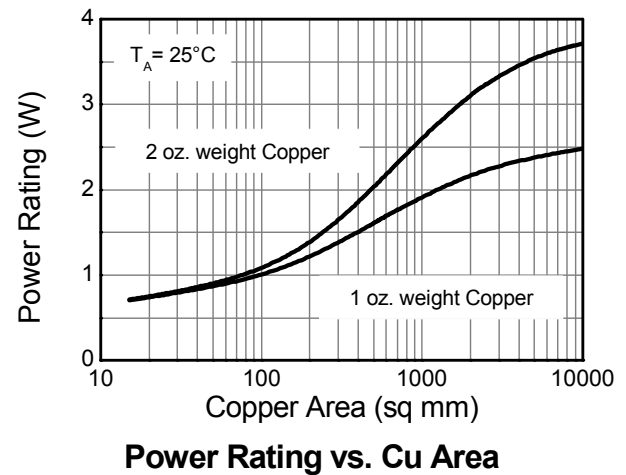
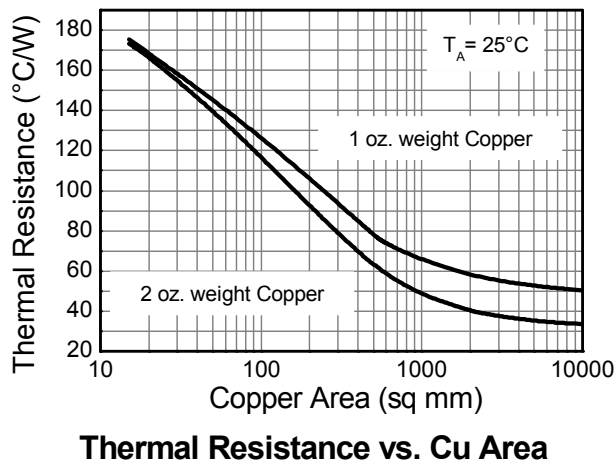
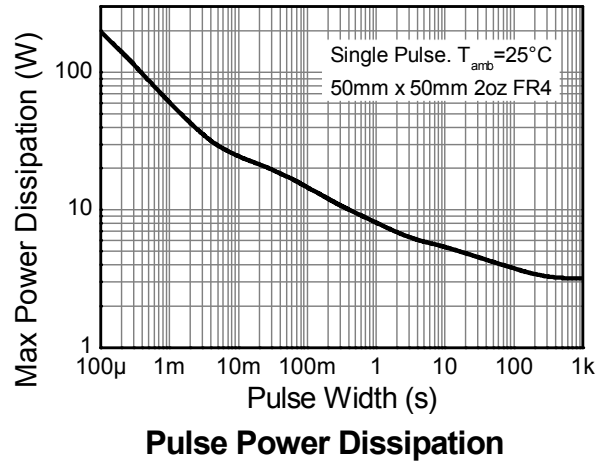
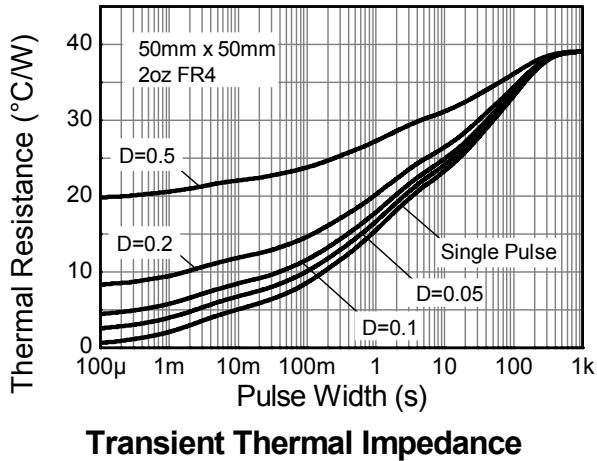
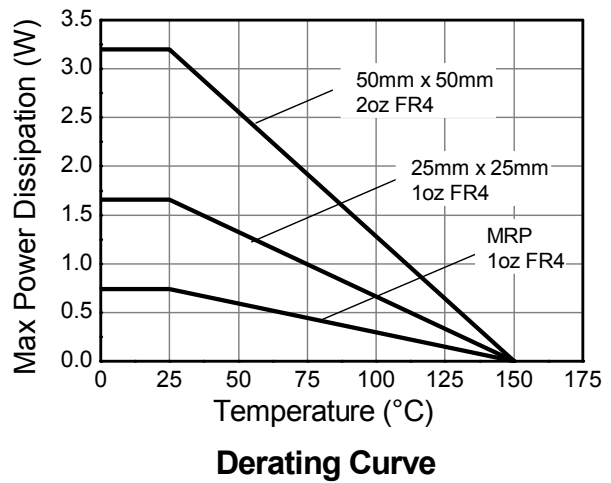
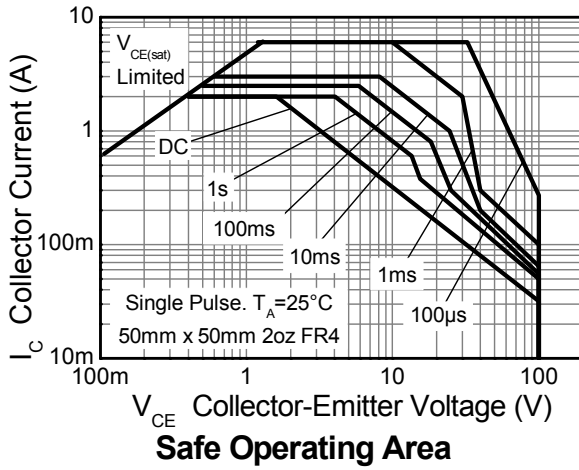
Characteristic	Symbol	Value	Unit
Power Dissipation	$P_D$	(Note 5)	3.2
		(Note 6)	1.7
		(Note 7)	0.74
Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	(Note 5)	39
		(Note 6)	75
		(Note 7)	169
Thermal Resistance, Junction to Leads	$R_{\theta JL}$	9	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**ESD Ratings** (Note 9)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- For a device mounted with the exposed collector pad on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  - Same as note (5), except mounted on 25mm x 25mm 1oz copper.
  - Same as note (5), except mounted on minimum recommended pad (MRP) layout.
  - Thermal resistance from junction to solder-point (on the exposed collector pad).
  - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

**Thermal Characteristics and Derating Information**

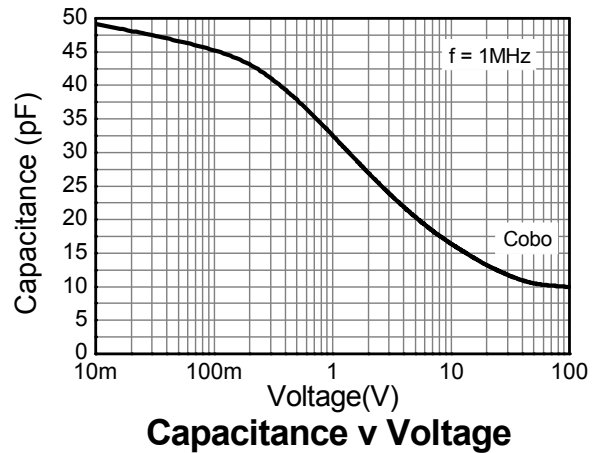
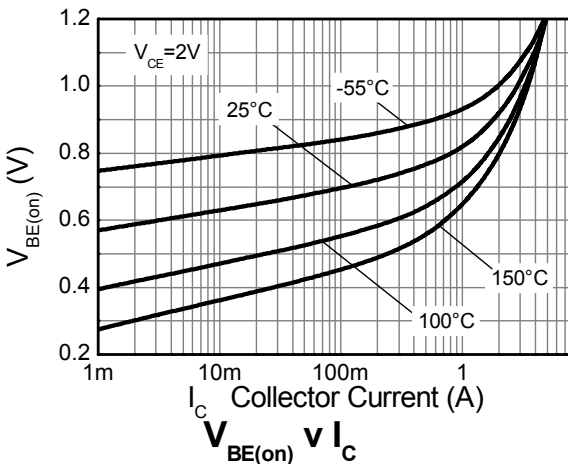
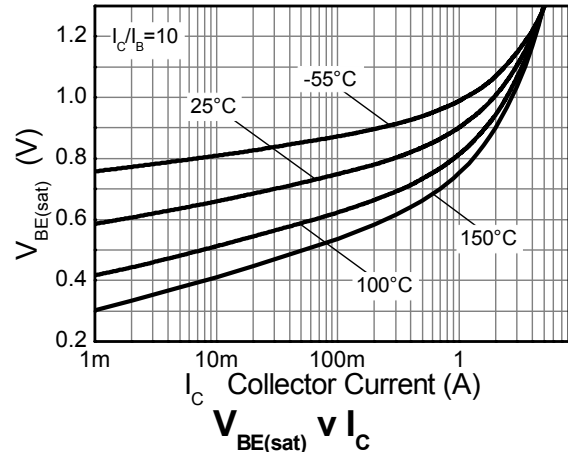
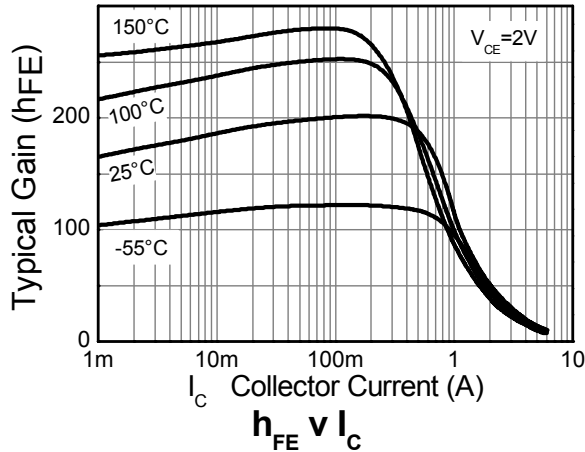
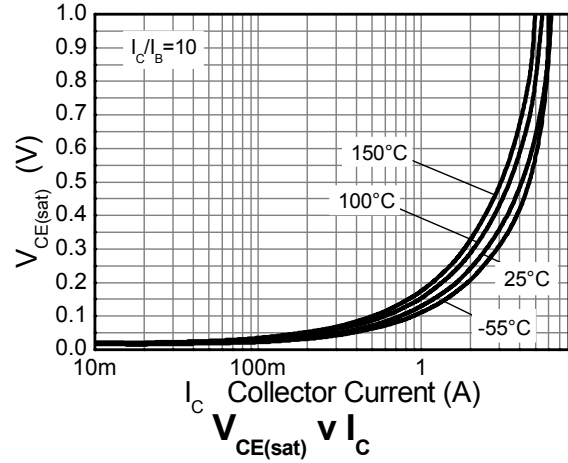
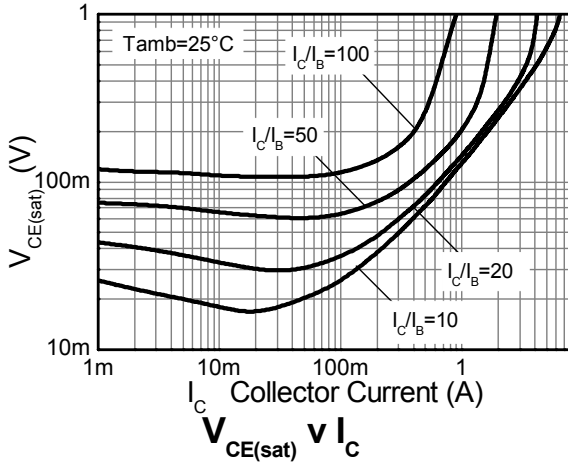


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	120	—	—	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV <sub>CEO</sub>	100	—	—	V	I <sub>C</sub> = 10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	5	—	—	V	I <sub>E</sub> = 100μA
Collector Cutoff Current	I <sub>CBO</sub>	—	—	0.1 10	μA	V <sub>CB</sub> = 100V V <sub>CB</sub> = 100V, T <sub>AMB</sub> = +100°C
Emitter Cutoff Current	I <sub>EBO</sub>	—	—	0.1	μA	V <sub>EB</sub> = 4V
Collector-Emitter Saturation Voltage (Note 10)	V <sub>CE(sat)</sub>	—	0.13 0.23	0.3 0.5	V	I <sub>C</sub> = 1A, I <sub>B</sub> = 100mA I <sub>C</sub> = 2A, I <sub>B</sub> = 200mA
Base-Emitter Saturation Voltage (Note 10)	V <sub>BE(sat)</sub>	—	0.9	1.25	V	I <sub>C</sub> = 1A, I <sub>B</sub> = 100mA
Base-Emitter Turn-On Voltage (Note 10)	V <sub>BE(on)</sub>	—	0.8	1.00	V	I <sub>C</sub> = 1A, V <sub>CE</sub> = 2V
DC Current Gain (Note 10)	h <sub>FE</sub>	70 100 55 25	200 200 110 55	— 300 — —	—	I <sub>C</sub> = 50mA, V <sub>CE</sub> = 2V I <sub>C</sub> = 500mA, V <sub>CE</sub> = 2V I <sub>C</sub> = 1A, V <sub>CE</sub> = 2V I <sub>C</sub> = 2A, V <sub>CE</sub> = 2V
Transition Frequency	f <sub>T</sub>	140	175	—	MHz	I <sub>C</sub> = 100mA, V <sub>CE</sub> = 5V f = 100MHz
Output Capacitance	C <sub>obo</sub>	—	—	30	pF	V <sub>CB</sub> = 10A, f = 1MHz
Switching Times	t <sub>on</sub> t <sub>off</sub>	—	80 1200	—	ns ns	I <sub>C</sub> = 500mA, V <sub>CC</sub> = 10V, I <sub>B1</sub> = I <sub>B2</sub> = 50mA

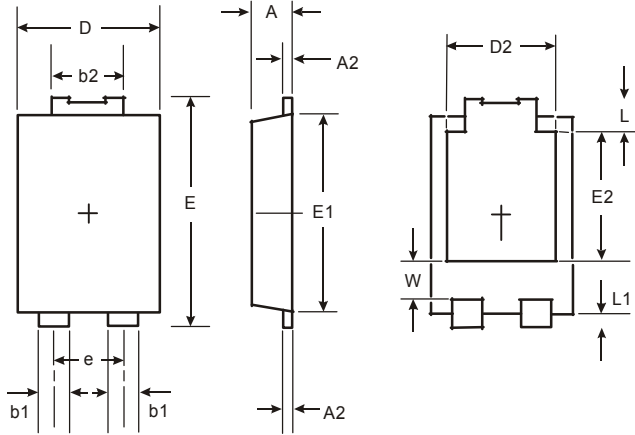
Note: 10. Pulse Test: Pulse width ≤ 300μs. Duty cycle ≤ 2.0%.

**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



**Package Outline Dimensions**

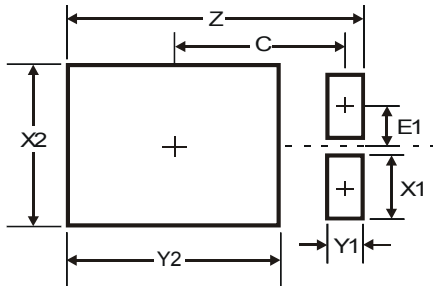
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



PowerDI <sup>5</sup>		
Dim	Min	Max
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.054 Typ	
E	6.40	6.60
e	1.84 Typ	
E1	5.30	5.45
E2	3.549 Typ	
L	0.75	0.95
L1	0.50	0.65
W	1.10	1.41
All Dimensions in mm		

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for latest version.



Dimensions	Value (in mm)
Z	6.6
X1	1.4
X2	3.6
Y1	0.8
Y2	4.7
C	3.87
E1	0.9

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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